

AI / HPC LIQUID COOLING SYSTEM

High Density Computing Thermal Architecture

SYSTEM FLOW | 系統架構

CPU / GPU Cold Plate → Quick Disconnect → Manifold / CDU → Heat Exchanger

- ✓ High efficiency thermal management
- ✓ Scalable rack-level architecture
- ✓ Mission-critical reliability

◆ Cold Plate (CPU / GPU Cooling)

- ✓ Ultra-high thermal conductivity
- ✓ CPU / GPU / AI accelerator cooling
- ✓ Precision engineered cold plate



◆ Quick Disconnect Coupling (QD/UQD)

- ✓ Leak-free rapid maintenance
- ✓ Rack modular design
- ✓ High reliability connection



◆ Manifold / Distribution System

- ✓ Balanced coolant distribution
- ✓ High-density server support
- ✓ Customizable interface design



◆ Tubing System (Cooling Pipe)

- ✓ High pressure durability
- ✓ Flexible system integration
- ✓ Scalable architecture



SERVICE CAPABILITY | ENGINEERING SUPPORT

- ✓ DFM & Thermal Simulation
- ✓ Rapid Prototyping & PPAP Support
- ✓ Mass Production Scaling
- ✓ Global Supply Chain Integration

CONTACT

Contact us for more information www.vekooler.com